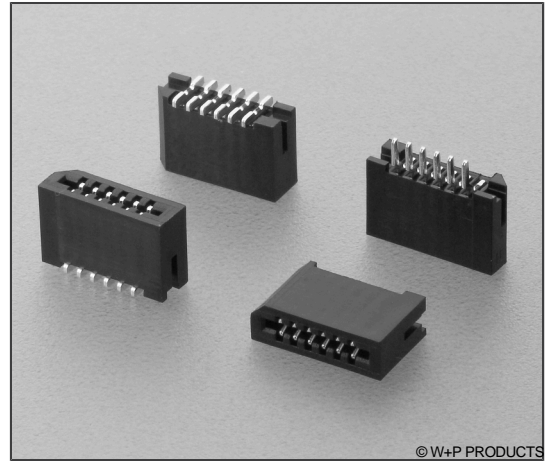


SMT LIF-Verbinder für FFC / FPC, RM 1,00mm, stehend/liegend SMT LIF Connectors for FFC / FPC, 1.00mm Pitch, Vertical/Horizontal

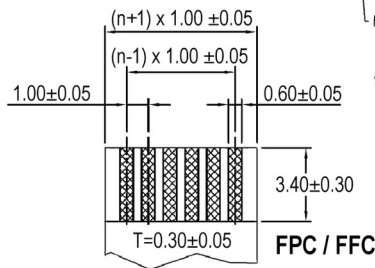
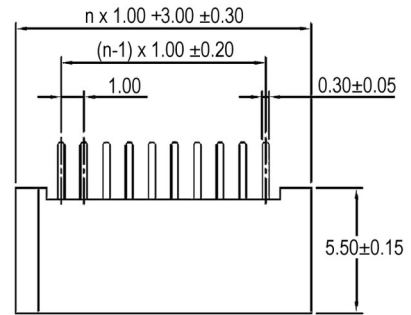
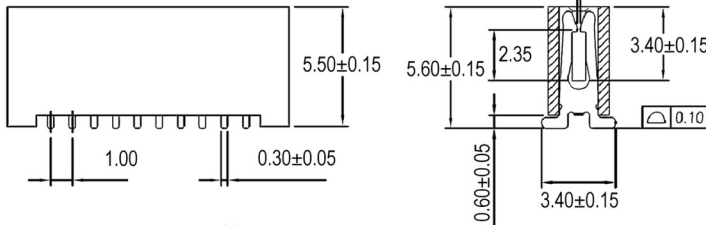
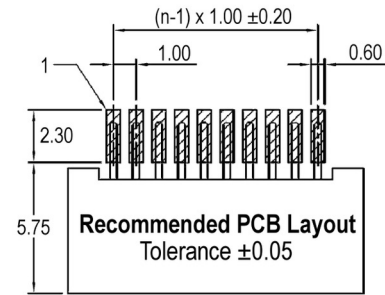
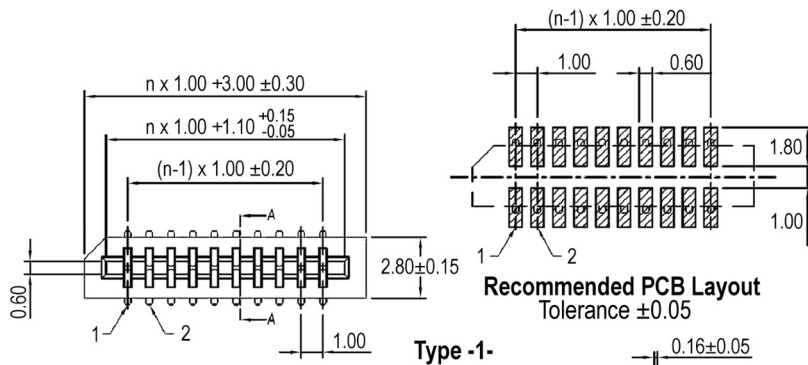
Technische Daten / Technical Data

Isolierkörper <i>Insulator</i>	Thermoplast, nach UL94 V-0 <i>Thermoplastic, rated UL94 V-0</i>
Kontaktmaterial <i>Contact Material</i>	Kupferlegierung <i>Copper alloy</i>
Durchgangswiderstand <i>Contact Resistance</i>	< 30 mΩ <i>< 30 mΩ</i>
Isolationswiderstand <i>Insulation Resistance</i>	> 500 MΩ <i>> 500 MΩ</i>
Spannungsfestigkeit <i>Test Voltage</i>	500 V AC <i>500 V AC</i>
Nennstrom <i>Current Rating</i>	0,5 A <i>0,5 A</i>
Temperaturbereich <i>Temperature Range</i>	-20 °C ... +85 °C <i>-20 °C ... +85 °C</i>
Verarbeitung <i>Processing</i>	Reflow-Lötverfahren <i>Reflow soldering</i>

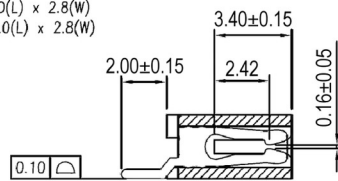


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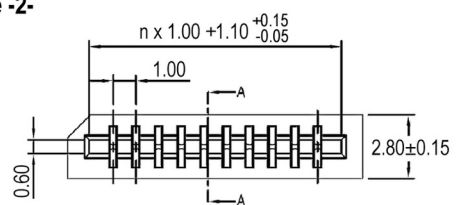
Passendes Flex-Kabel:
Compatible Flex Cables:
599



Mylar (FILM)
3P~5P : 4.0(L) x 2.8(W)
6P~13P : 8.0(L) x 2.8(W)
14P~30P : 12.0(L) x 2.8(W)



Type-2-



Series	Contacts*	Type*	Plating	Packaging*
5593	08 03-30	2 1 Top entry 2 Side entry	50 50 Verzinkt Tin plated	TR ST TR (Option) FTR (Option)

Lieferformen / Packaging Options:

ST In Stangen ohne Pick&Place-Pads / *In tubes w/o Pick&Place-Pads*
TR (Option) Tape & Reel / *Tape & Reel*
FTR (Option) Tape & Reel, Film Tape (nur Type 1) / *Tape & Reel, Film Pad (Type 1 only)*

* Dies ist ein **Bestellbeispiel** - bitte durch Ihre Spezifikationen ersetzen.
* This is an **order example** - please replace by your specifications.

Informationen zum Reflow-Lötverfahren Reflow Soldering Information

Reflow-Lötempfehlung für kurze Lötzeiten

Die Bauteile sollten gemäß folgendem Temperatur-Profil in Anlehnung an die IPC/JEDEC J-STD-020C für bleifreies Löten im Reflow-Verfahren verarbeitet werden (Maximalwerte).

Profileigenschaft	Kennwert
Temperatur Minimum T_{Smin}	150 °C
Temperatur Maximum T_{Smax}	200 °C
Dauer $T_{Smin} - T_{Smax}$	60 – 180s
Temperatur Lötbereich T_L	217 °C
Verweildauer oberhalb T_L	60 – 180s
Ramp-Up Rate $T_{Smax} - T_P$	max. 3 °C / s
Höchsttemperatur T_P	260±5 °C
Dauer Höchsttemperatur	20 – 40s
Ramp-Down Rate $T_{Pmax} - T_{Smin}$	6 °C / s
Dauer 25 °C – Höchsttemperatur T_P	max. 8m

Reflow Soldering Recommendation For Shorter Peak Times

Items should be soldered according to IPC/JEDEC J-STD-020C temperature profile for leadfree reflow soldering (maximum values).

Profile Feature	Key Values
Minimum Temperature T_{Smin}	150 °C
Maximum Temperatur T_{Smax}	200 °C
Duration $T_{Smin} - T_{Smax}$	60 – 180s
Soldering Range Temperature T_L	217 °C
Duration above T_L	60 – 180s
Ramp-Up Rate $T_{Smax} - T_P$	max. 3 °C / s
Peak Temperature T_P	260±5 °C
Duration Peak Temperature	20 – 40s
Ramp-Down Rate $T_{Pmax} - T_{Smin}$	6 °C / s
Duration 25°C - Peak Temp. T_P	max. 8min

